Electronic Patent Application Fee Transmittal								
Application Number:	10551745							
Filing Date:	19-Mar-2007							
Title of Invention:	Diffusion Soldered Semiconductor Device and Method							
First Named Inventor/Applicant Name:	Edmund Riedl							
Filer:	Mark L. Gleason/Michelle Murphy							
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Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:								
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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